Terminated VIN+ with 50 ohms for SE input at VIN+.

Let C22, C30 and C32 share a pad on the common net. Let C23, C31 and C24 share a pad on the common net.

Let R18 and R19 share a pad on the common net. Let VDD and R21 share a pad on the common net.

The IC pad is the only ground connection for this IC. Ensure good connection through multiple vias to the PCB ground plane.

Locate VIN+ SE, TMST+ TMST- at edge opposite FMC connector.

VIN+ is the only ground connection for this IC. Ensure good connection through multiple vias to the PCB ground plane.

Priorities for placement:
1. Decoupling caps closer to IC.
2. _VIN_ _VIN_ _VIN_ _VIN_ _VIN_ close to IC.

VIN_ SE, TMST+, TMST- at edge opposite FMC connector.

VIN+ is the only ground connection for this IC. Ensure good connection through multiple vias to the PCB ground plane.

Locate VIN+ SE, TMST+, TMST- at edge opposite FMC connector.

VIN+ is the only ground connection for this IC. Ensure good connection through multiple vias to the PCB ground plane.

Locate close to UDA output pin to minimize noise.

The IC pad is the only ground connection for this IC. Ensure good connection through multiple vias to the PCB ground plane.

The IC pad is the only ground connection for this IC. Ensure good connection through multiple vias to the PCB ground plane.
RF Sampling 4GSPS ADC with 8 GHz Amplifier

Designed for: Internal Use Only

Project Title: TSW12J54EVM_A_8_Hardware.SchDoc

Sheet Title: TSW12J54EVM_A_8_Hardware.SchDoc

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Drawn By: Jim Brinkhurst

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